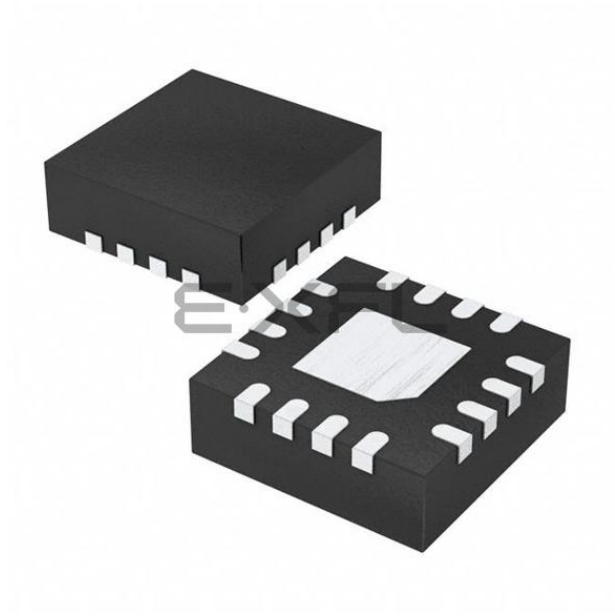

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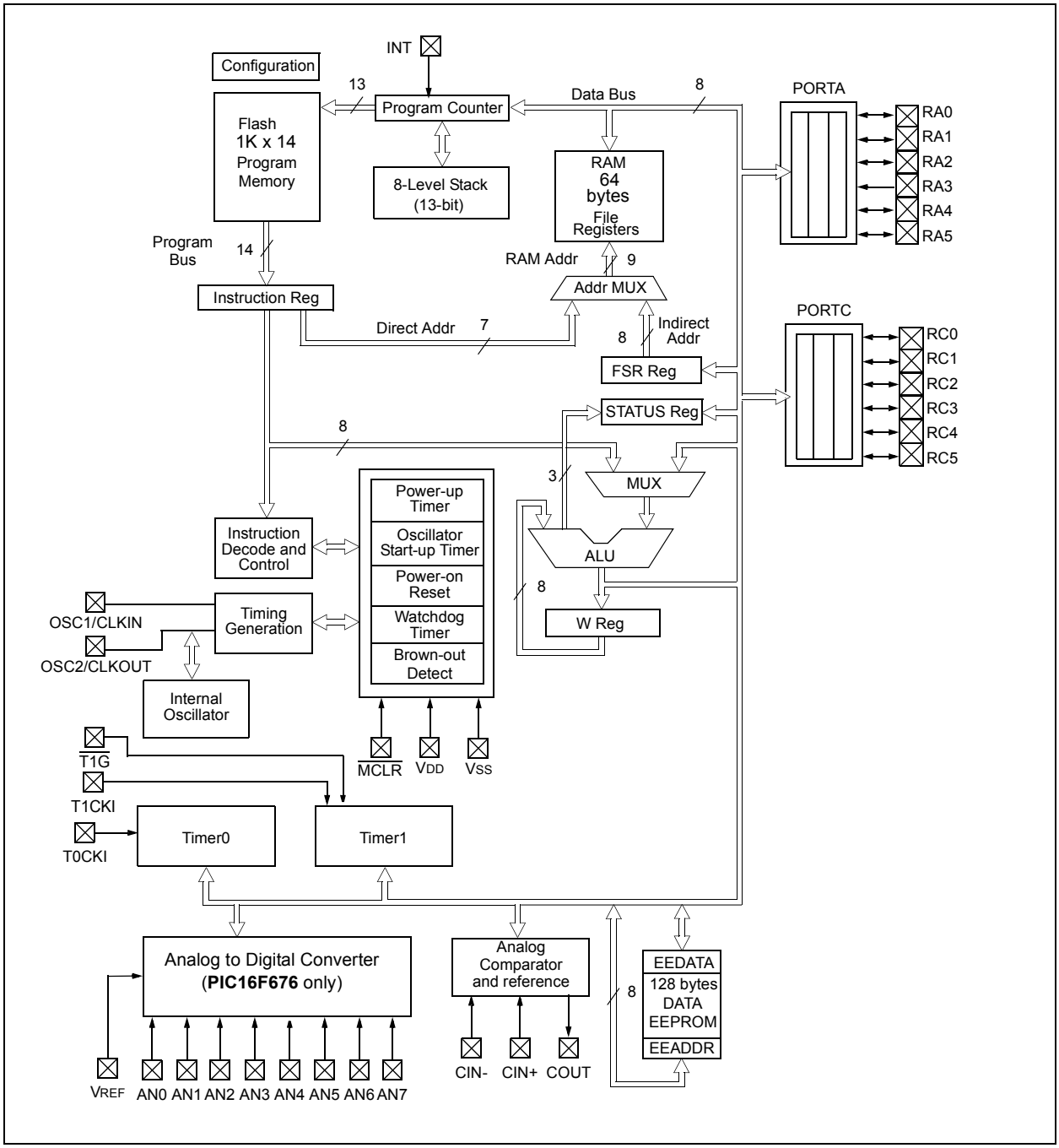
Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	-
Peripherals	Brown-out Detect/Reset, POR, WDT
Number of I/O	12
Program Memory Size	1.75KB (1K x 14)
Program Memory Type	FLASH
EEPROM Size	128 x 8
RAM Size	64 x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 5.5V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	16-VQFN Exposed Pad
Supplier Device Package	16-QFN (4x4)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16f630-i-ml

1.0 DEVICE OVERVIEW

This document contains device specific information for the PIC16F630/676. Additional information may be found in the PIC® Mid-Range Reference Manual (DS33023), which may be obtained from your local Microchip Sales Representative or downloaded from the Microchip web site. The Reference Manual should be considered a complementary document to this Data Sheet and is highly recommended reading for a better understanding of the device architecture and operation of the peripheral modules.

The PIC16F630 and PIC16F676 devices are covered by this Data Sheet. They are identical, except the PIC16F676 has a 10-bit A/D converter. They come in 14-pin PDIP, SOIC and TSSOP packages. Figure 1-1 shows a block diagram of the PIC16F630/676 devices. Table 1-1 shows the pinout description.

FIGURE 1-1: PIC16F630/676 BLOCK DIAGRAM



2.2.2 SPECIAL FUNCTION REGISTERS

The Special Function Registers are registers used by the CPU and peripheral functions for controlling the desired operation of the device (see Table 2-1). These registers are static RAM.

The special registers can be classified into two sets: core and peripheral. The Special Function Registers associated with the “core” are described in this section. Those related to the operation of the peripheral features are described in the section of that peripheral feature.

FIGURE 2-2: DATA MEMORY MAP OF THE PIC16F630/676

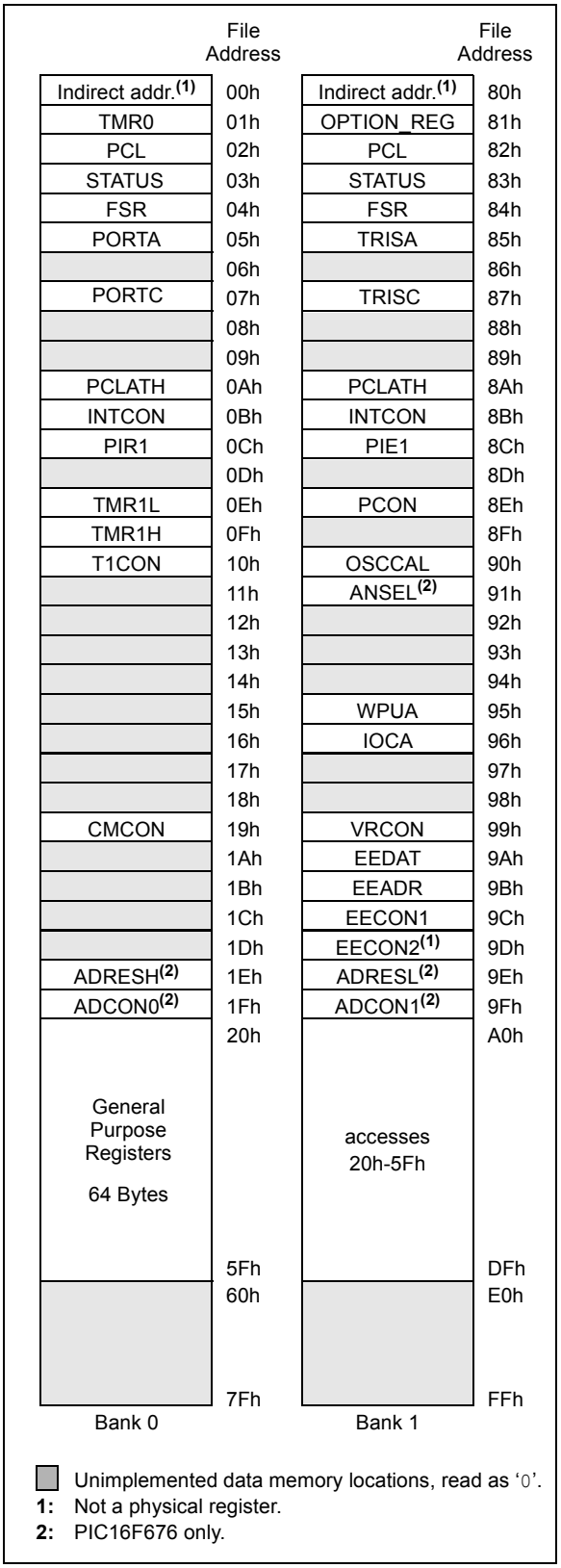


TABLE 2-1: PIC16F630/676 SPECIAL REGISTERS SUMMARY BANK 0

Addr	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOD	Page
Bank 0											
00h	INDF	Addressing this location uses contents of FSR to address data memory (not a physical register)								xxxx xxxx	20,63
01h	TMR0	Timer0 Module's Register								xxxx xxxx	31
02h	PCL	Program Counter's (PC) Least Significant Byte								0000 0000	19
03h	STATUS	IRP(2)	RP1(2)	RP0	$\overline{TO}$	$\overline{PD}$	Z	DC	C	0001 1xxx	13
04h	FSR	Indirect data memory Address Pointer								xxxx xxxx	20
05h	PORTA	—	—	I/O Control Registers						--xx xxxx	21
06h	—	Unimplemented								—	—
07h	PORTC	—	—	I/O Control Registers						--xx xxxx	28
08h	—	Unimplemented								—	—
09h	—	Unimplemented								—	—
0Ah	PCLATH	—	—	—	Write buffer for upper 5 bits of program counter					---0 0000	19
0Bh	INTCON	GIE	PEIE	T0IE	INTE	RAIE	T0IF	INTF	RAIF	0000 0000	15
0Ch	PIR1	EEIF	ADIF	—	—	CMIF	—	—	TMR1IF	00-- 0--0	17
0Dh	—	Unimplemented								—	—
0Eh	TMR1L	Holding register for the Least Significant Byte of the 16-bit TMR1								xxxx xxxx	34
0Fh	TMR1H	Holding register for the Most Significant Byte of the 16-bit TMR1								xxxx xxxx	34
10h	T1CON	—	T1GE	T1CKPS1	T1CKPS0	T1OSCEN	$\overline{T1SYNC}$	TMR1CS	TMR1ON	-000 0000	36
11h	—	Unimplemented								—	—
12h	—	Unimplemented								—	—
13h	—	Unimplemented								—	—
14h	—	Unimplemented								—	—
15h	—	Unimplemented								—	—
16h	—	Unimplemented								—	—
17h	—	Unimplemented								—	—
18h	—	Unimplemented								—	—
19h	CMCON	—	COUT	—	CINV	CIS	CM2	CM1	CM0	-0-0 0000	39
1Ah	—	Unimplemented								—	—
1Bh	—	Unimplemented								—	—
1Ch	—	Unimplemented								—	—
1Dh	—	Unimplemented								—	—
1Eh	ADRESH(3)	Most Significant 8 bits of the left shifted A/D result or 2 bits of right shifted result								xxxx xxxx	46
1Fh	ADCON0(3)	ADFM	VCFG	—	CHS2	CHS1	CHS0	GO/$\overline{DONE}$	ADON	00-0 0000	47,63

Legend: – = Unimplemented locations read as '0', u = unchanged, x = unknown, q = value depends on condition shaded = unimplemented

Note 1: Other (non Power-up) Resets include $\overline{MCLR}$ Reset, Brown-out Detect and Watchdog Timer Reset during normal operation.

2: IRP and RP1 bits are reserved, always maintain these bits clear.

3: PIC16F676 only.

TABLE 2-2: PIC16F630/676 SPECIAL FUNCTION REGISTERS SUMMARY BANK 1

Addr	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOD	Page
Bank 1											
80h	INDF	Addressing this location uses contents of FSR to address data memory (not a physical register)								xxxx xxxx	20,63
81h	OPTION_REG	$\overline{\text{RAPU}}$	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0	1111 1111	14,32
82h	PCL	Program Counter's (PC) Least Significant Byte								0000 0000	19
83h	STATUS	IRP(2)	RP1(2)	RP0	$\overline{\text{TO}}$	$\overline{\text{PD}}$	Z	DC	C	0001 1xxx	13
84h	FSR	Indirect data memory Address Pointer								xxxx xxxx	20
85h	TRISA	—	—	TRISA5	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	--11 1111	21
86h	—	Unimplemented								—	—
87h	TRISC	—	—	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0	--11 1111	—
88h	—	Unimplemented								—	—
89h	—	Unimplemented								—	—
8Ah	PCLATH	—	—	—	Write buffer for upper 5 bits of program counter					---0 0000	19
8Bh	INTCON	GIE	PEIE	T0IE	INTE	RAIE	T0IF	INTF	RAIF	0000 0000	15
8Ch	PIE1	EEIE	ADIE	—	—	CMIE	—	—	TMR1IE	00-- 0--0	16
8Dh	—	Unimplemented								—	—
8Eh	PCON	—	—	—	—	—	—	$\overline{\text{POR}}$	$\overline{\text{BOD}}$	---- --qq	18
8Fh	—									—	
90h	OSCCAL	CAL5	CAL4	CAL3	CAL2	CAL1	CAL0	—	—	1000 00--	18
91h	ANSEL(3)	ANS7	ANS6	ANS5	ANS4	ANS3	ANS2	ANS1	ANS0	1111 1111	48
92h	—	Unimplemented								—	—
93h	—	Unimplemented								—	—
94h	—	Unimplemented								—	—
95h	WPUA	—	—	WPUA5	WPUA4	—	WPUA2	WPUA1	WPUA0	--11 -111	22
96h	IOCA	—	—	IOCA5	IOCA4	IOCA3	IOCA2	IOCA1	IOCA0	--00 0000	23
97h	—	Unimplemented								—	—
98h	—	Unimplemented								—	—
99h	VRCON	VREN	—	VRR	—	VR3	VR2	VR1	VR0	0-0- 0000	44
9Ah	EEDAT	EEPROM data register								0000 0000	51
9Bh	EEADR	—	EEPROM address register							0000 0000	51
9Ch	EECON1	—	—	—	—	WRERR	WREN	WR	RD	---- x000	52
9Dh	EECON2	EEPROM control register 2 (not a physical register)								---- ----	51
9Eh	ADRESL(3)	Least Significant 2 bits of the left shifted result or 8 bits of the right shifted result								xxxx xxxx	46
9Fh	ADCON1(3)	—	ADCS2	ADCS1	ADCS0	—	—	—	—	-000 ----	47,63

Legend: – = Unimplemented locations read as '0', u = unchanged, x = unknown, q = value depends on condition, shaded = unimplemented

Note 1: Other (non Power-up) Resets include $\overline{\text{MCLR}}$ Reset, Brown-out Detect and Watchdog Timer Reset during normal operation.

2: IRP and RP1 bits are reserved, always maintain these bits clear.

3: PIC16F676 only.

5.0 TIMER1 MODULE WITH GATE CONTROL

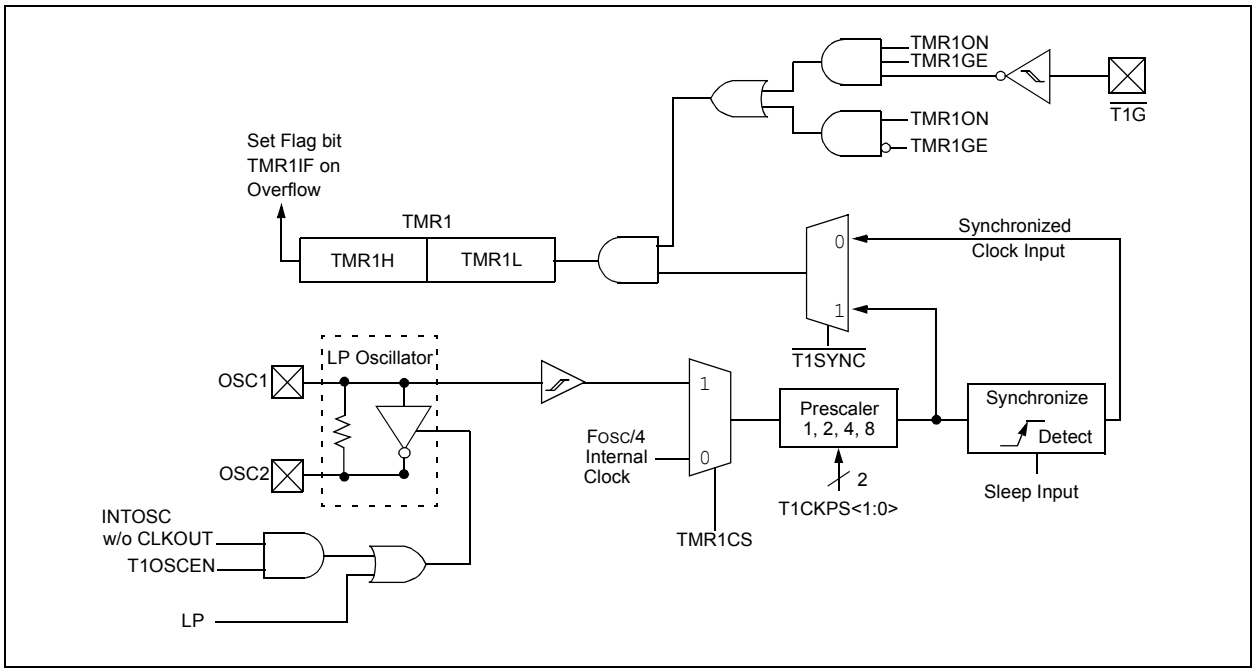
The PIC16F630/676 devices have a 16-bit timer. Figure 5-1 shows the basic block diagram of the Timer1 module. Timer1 has the following features:

- 16-bit timer/counter (TMR1H:TMR1L)
- Readable and writable
- Internal or external clock selection
- Synchronous or asynchronous operation
- Interrupt on overflow from FFFFh to 0000h
- Wake-up upon overflow (Asynchronous mode)
- Optional external enable input ($\overline{T1G}$)
- Optional LP oscillator

The Timer1 Control register (T1CON), shown in Register 5-1, is used to enable/disable Timer1 and select the various features of the Timer1 module.

Note:	Additional information on timer modules is available in the PIC® Mid-Range Reference Manual, (DS33023).

FIGURE 5-1: TIMER1 BLOCK DIAGRAM



5.4 Timer1 Operation in Asynchronous Counter Mode

If control bit $\overline{\text{T1SYNC}}$ (T1CON<2>) is set, the external clock input is not synchronized. The timer continues to increment asynchronous to the internal phase clocks. The timer will continue to run during Sleep and can generate an interrupt on overflow, which will wake-up the processor. However, special precautions in software are needed to read/write the timer (Section 5.4.1).

Note:	The ANSEL (91h) and CMCON (19h) registers must be initialized to configure an analog channel as a digital input. Pins configured as analog inputs will read '0'. The ANSEL register is defined for the PIC16F676.

5.4.1 READING AND WRITING TIMER1 IN ASYNCHRONOUS COUNTER MODE

Reading TMR1H or TMR1L, while the timer is running from an external asynchronous clock, will ensure a valid read (taken care of in hardware). However, the user should keep in mind that reading the 16-bit timer in two 8-bit values itself, poses certain problems, since the timer may overflow between the reads.

For writes, it is recommended that the user simply stop the timer and write the desired values. A write contention may occur by writing to the timer registers, while the register is incrementing. This may produce an unpredictable value in the timer register.

Reading the 16-bit value requires some care. Examples 12-2 and 12-3 in the PIC® Mid-Range MCU Family Reference Manual (DS33023) show how to read and write Timer1 when it is running in Asynchronous mode.

5.5 Timer1 Oscillator

A crystal oscillator circuit is built-in between pins OSC1 (input) and OSC2 (amplifier output). It is enabled by setting control bit T1OSCEN (T1CON<3>). The oscillator is a low power oscillator rated up to 32 kHz. It will continue to run during Sleep. It is primarily intended for a 32 kHz crystal. Table 9-2 shows the capacitor selection for the Timer1 oscillator.

The Timer1 oscillator is shared with the system LP oscillator. Thus, Timer1 can use this mode only when the system clock is derived from the internal oscillator. As with the system LP oscillator, the user must provide a software time delay to ensure proper oscillator start-up.

TRISA5 and TRISA4 bits are set when the Timer1 oscillator is enabled. RA5 and RA4 read as '0' and TRISA5 and TRISA4 bits read as '1'.

Note:	The oscillator requires a start-up and stabilization time before use. Thus, T1OSCEN should be set and a suitable delay observed prior to enabling Timer1.

5.6 Timer1 Operation During Sleep

Timer1 can only operate during Sleep when setup in Asynchronous Counter mode. In this mode, an external crystal or clock source can be used to increment the counter. To setup the timer to wake the device:

- Timer1 must be on (T1CON<0>)
- TMR1IE bit (PIE1<0>) must be set
- PEIE bit (INTCON<6>) must be set

The device will wake-up on an overflow. If the GIE bit (INTCON<7>) is set, the device will wake-up and jump to the Interrupt Service Routine on an overflow.

TABLE 5-1: REGISTERS ASSOCIATED WITH TIMER1 AS A TIMER/COUNTER

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOD	Value on all other Resets
0Bh/8Bh	INTCON	GIE	PEIE	T0IE	INTE	RAIE	T0IF	INTF	RAIF	0000 0000	0000 000u
0Ch	PIR1	EEIF	ADIF	—	—	CMIF	—	—	TMR1IF	00-- 0--0	00-- 0--0
0Eh	TMR1L	Holding Register for the Least Significant Byte of the 16-bit TMR1 Register								xxxx xxxx	uuuu uuuu
0Fh	TMR1H	Holding Register for the Most Significant Byte of the 16-bit TMR1 Register								xxxx xxxx	uuuu uuuu
10h	T1CON	—	TMR1GE	T1CKPS1	T1CKPS0	T1OSCEN	$\overline{\text{T1SYNC}}$	TMR1CS	TMR1ON	-000 0000	-uuu uuuu
8Ch	PIE1	EEIE	ADIE	—	—	CMIE	—	—	TMR1IE	00-- 0--0	00-- 0--0

Legend: x = unknown, u = unchanged, - = unimplemented, read as '0'. Shaded cells are not used by the Timer1 module.

NOTES:

6.0 COMPARATOR MODULE

The PIC16F630/676 devices have one analog comparator. The inputs to the comparator are multiplexed with the RA0 and RA1 pins. There is an on-chip Comparator Voltage Reference that can also be applied to an input of the comparator. In addition, RA2 can be configured as the comparator output. The Comparator Control Register (CMCON), shown in Register 6-1, contains the bits to control the comparator.

REGISTER 6-1: CMCON — COMPARATOR CONTROL REGISTER (ADDRESS: 19h)

U-0	R-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	COUT	—	CINV	CIS	CM2	CM1	CM0
bit 7							bit 0

bit 7 **Unimplemented**: Read as '0'

bit 6 **COUT**: Comparator Output bit
When CINV = 0:
1 = VIN+ > VIN-
0 = VIN+ < VIN-
When CINV = 1:
1 = VIN+ < VIN-
0 = VIN+ > VIN-

bit 5 **Unimplemented**: Read as '0'

bit 4 **CINV**: Comparator Output Inversion bit
1 = Output inverted
0 = Output not inverted

bit 3 **CIS**: Comparator Input Switch bit
When CM2:CM0 = 110 or 101:
1 = VIN- connects to CIN+
0 = VIN- connects to CIN-

bit 2-0 **CM2:CM0**: Comparator Mode bits
Figure 6-2 shows the Comparator modes and CM2:CM0 bit settings

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
- n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

6.1 Comparator Operation

A single comparator is shown in Figure 6-1, along with the relationship between the analog input levels and the digital output. When the analog input at VIN+ is less than the analog input VIN-, the output of the comparator is a digital low level. When the analog input at VIN+ is greater than the analog input VIN-, the output of the comparator is a digital high level. The shaded areas of the output of the comparator in Figure 6-1 represent the uncertainty due to input offsets and response time.

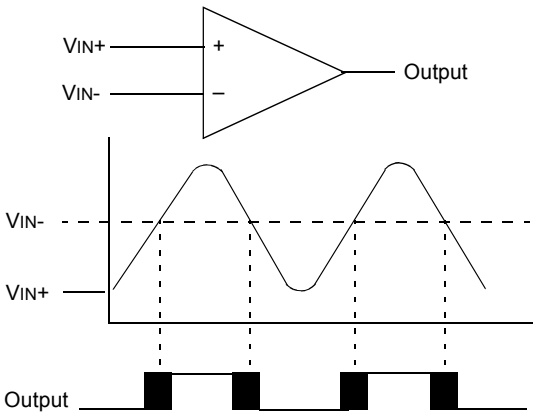
Note:	To use CIN+ and CIN- pins as analog inputs, the appropriate bits must be programmed in the CMCON (19h) register.

The polarity of the comparator output can be inverted by setting the CINV bit (CMCON<4>). Clearing CINV results in a non-inverted output. A complete table showing the output state versus input conditions and the polarity bit is shown in Table 6-1.

TABLE 6-1: OUTPUT STATE VS. INPUT CONDITIONS

Input Conditions	CINV	COUT
VIN- > VIN+	0	0
VIN- < VIN+	0	1
VIN- > VIN+	1	1
VIN- < VIN+	1	0

FIGURE 6-1: SINGLE COMPARATOR



Note: CINV bit (CMCON<4>) is clear.

8.0 DATA EEPROM MEMORY

The EEPROM data memory is readable and writable during normal operation (full V_{DD} range). This memory is not directly mapped in the register file space. Instead, it is indirectly addressed through the Special Function Registers. There are four SFRs used to read and write this memory:

- EECON1
- EECON2 (not a physically implemented register)
- EEDATA
- EEADR

EEDATA holds the 8-bit data for read/write, and EEADR holds the address of the EEPROM location being accessed. PIC16F630/676 devices have 128 bytes of data EEPROM with an address range from 0h to 7Fh.

The EEPROM data memory allows byte read and write. A byte write automatically erases the location and writes the new data (erase before write). The EEPROM data memory is rated for high erase/write cycles. The write time is controlled by an on-chip timer. The write time will vary with voltage and temperature as well as from chip to chip. Please refer to AC Specifications for exact limits.

When the data memory is code-protected, the CPU may continue to read and write the data EEPROM memory. The device programmer can no longer access this memory.

Additional information on the data EEPROM is available in the PIC® Mid-Range Reference Manual, (DS33023).

REGISTER 8-1: EEDAT — EEPROM DATA REGISTER (ADDRESS: 9Ah)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
EEDAT7	EEDAT6	EEDAT5	EEDAT4	EEDAT3	EEDAT2	EEDAT1	EEDAT0
bit 7							bit 0

bit 7-0 **EEDATn**: Byte value to write to or read from data EEPROM

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
- n = Value at POR	’1’ = Bit is set	’0’ = Bit is cleared	x = Bit is unknown

REGISTER 8-2: EEADR — EEPROM ADDRESS REGISTER (ADDRESS: 9Bh)

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	EADR6	EADR5	EADR4	EADR3	EADR2	EADR1	EADR0
bit 7							bit 0

bit 7 **Unimplemented**: Should be set to ‘0’

bit 6-0 **EEADR**: Specifies one of 128 locations for EEPROM Read/Write Operation

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
- n = Value at POR	’1’ = Bit is set	’0’ = Bit is cleared	x = Bit is unknown

9.2 Oscillator Configurations

9.2.1 OSCILLATOR TYPES

The PIC16F630/676 can be operated in eight different Oscillator Option modes. The user can program three Configuration bits (FOSC2 through FOSC0) to select one of these eight modes:

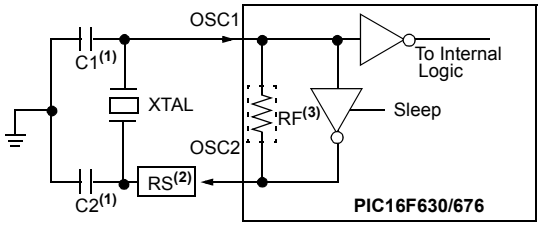
- LP Low-Power Crystal
- XT Crystal/Resonator
- HS High Speed Crystal/Resonator
- RC External Resistor/Capacitor (2 modes)
- INTOSC Internal Oscillator (2 modes)
- EC External Clock In

Note: Additional information on oscillator configurations is available in the PIC® Mid-Range Reference Manual, (DS33023).

9.2.2 CRYSTAL OSCILLATOR / CERAMIC RESONATORS

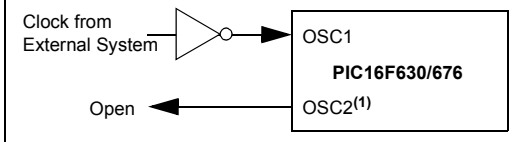
In XT, LP or HS modes a crystal or ceramic resonator is connected to the OSC1 and OSC2 pins to establish oscillation (see Figure 9-1). The PIC16F630/676 oscillator design requires the use of a parallel cut crystal. Use of a series cut crystal may yield a frequency outside of the crystal manufacturers specifications. When in XT, LP or HS modes, the device can have an external clock source to drive the OSC1 pin (see Figure 9-2).

FIGURE 9-1: CRYSTAL OPERATION (OR CERAMIC RESONATOR) (HS, XT OR LP OSC CONFIGURATION)



Note 1: See Table 9-1 and Table 9-2 for recommended values of C1 and C2.
2: A series resistor may be required for AT strip cut crystals.
3: RF varies with the Oscillator mode selected (Approx. value = 10 MΩ).

FIGURE 9-2: EXTERNAL CLOCK INPUT OPERATION (HS, XT, EC, OR LP OSC CONFIGURATION)



Note 1: Functions as RA4 in EC Osc mode.

TABLE 9-1: CAPACITOR SELECTION FOR CERAMIC RESONATORS

Ranges Characterized:			
Mode	**Freq**	**OSC1(C1)**	**OSC2(C2)**
XT	455 kHz 2.0 MHz 4.0 MHz	68-100 pF 15-68 pF 15-68 pF	68-100 pF 15-68 pF 15-68 pF
HS	8.0 MHz 16.0 MHz	10-68 pF 10-22 pF	10-68 pF 10-22 pF

Note 1: Higher capacitance increases the stability of the oscillator but also increases the start-up time. These values are for design guidance only. Since each resonator has its own characteristics, the user should consult the resonator manufacturer for appropriate values of external components.

TABLE 9-2: CAPACITOR SELECTION FOR CRYSTAL OSCILLATOR

Mode	Freq	OSC1(C1)	OSC2(C2)
LP	32 kHz	68-100 pF	68-100 pF
XT	100 kHz 2 MHz 4 MHz	68-150 pF 15-30 pF 15-30 pF	150-200 pF 15-30 pF 15-30 pF
HS	8 MHz 10 MHz 20 MHz	15-30 pF 15-30 pF 15-30 pF	15-30 pF 15-30 pF 15-30 pF

Note 1: Higher capacitance increases the stability of the oscillator but also increases the start-up time. These values are for design guidance only. Rs may be required in HS mode as well as XT mode to avoid overdriving crystals with low drive level specification. Since each crystal has its own characteristics, the user should consult the crystal manufacturer for appropriate values of external components.

TABLE 10-2: PIC16F630/676 INSTRUCTION SET

Mnemonic, Operands		Description	Cycles	14-Bit Opcode MSb LSb	Status Affected	Notes
BYTE-ORIENTED FILE REGISTER OPERATIONS						
ADDWF	f, d	Add W and f	1	00 0111 dfff ffff	C,DC,Z	**1,2**
ANDWF	f, d	AND W with f	1	00 0101 dfff ffff	Z	**1,2**
CLRF	f	Clear f	1	00 0001 lfff ffff	Z	**2**
CLRW	-	Clear W	1	00 0001 0xxx xxxx	Z	
COMF	f, d	Complement f	1	00 1001 dfff ffff	Z	**1,2**
DECF	f, d	Decrement f	1	00 0011 dfff ffff	Z	**1,2**
DECFSZ	f, d	Decrement f, Skip if 0	1(2)	00 1011 dfff ffff		**1,2,3**
INCF	f, d	Increment f	1	00 1010 dfff ffff	Z	**1,2**
INCFSZ	f, d	Increment f, Skip if 0	1(2)	00 1111 dfff ffff		**1,2,3**
IORWF	f, d	Inclusive OR W with f	1	00 0100 dfff ffff	Z	**1,2**
MOVF	f, d	Move f	1	00 1000 dfff ffff	Z	**1,2**
MOVWF	f	Move W to f	1	00 0000 lfff ffff		
NOP	-	No Operation	1	00 0000 0xx0 0000		
RLF	f, d	Rotate Left f through Carry	1	00 1101 dfff ffff	C	**1,2**
RRF	f, d	Rotate Right f through Carry	1	00 1100 dfff ffff	C	**1,2**
SUBWF	f, d	Subtract W from f	1	00 0010 dfff ffff	C,DC,Z	**1,2**
SWAPF	f, d	Swap nibbles in f	1	00 1110 dfff ffff		**1,2**
XORWF	f, d	Exclusive OR W with f	1	00 0110 dfff ffff	Z	**1,2**
BIT-ORIENTED FILE REGISTER OPERATIONS						
BCF	f, b	Bit Clear f	1	01 00bb bfff ffff		**1,2**
BSF	f, b	Bit Set f	1	01 01bb bfff ffff		**1,2**
BTFSC	f, b	Bit Test f, Skip if Clear	1 (2)	01 10bb bfff ffff		**3**
BTFSS	f, b	Bit Test f, Skip if Set	1 (2)	01 11bb bfff ffff		**3**
LITERAL AND CONTROL OPERATIONS						
ADDLW	k	Add literal and W	1	11 111x kkkk kkkk	C,DC,Z	
ANDLW	k	AND literal with W	1	11 1001 kkkk kkkk	Z	
CALL	k	Call subroutine	2	10 0kkk kkkk kkkk		
CLRWDT	-	Clear Watchdog Timer	1	00 0000 0110 0100	$\overline{TO}$,$\overline{PD}$	
GOTO	k	Go to address	2	10 1kkk kkkk kkkk		
IORLW	k	Inclusive OR literal with W	1	11 1000 kkkk kkkk	Z	
MOVLW	k	Move literal to W	1	11 00xx kkkk kkkk		
RETFIE	-	Return from interrupt	2	00 0000 0000 1001		
RETLW	k	Return with literal in W	2	11 01xx kkkk kkkk		
RETURN	-	Return from Subroutine	2	00 0000 0000 1000		
SLEEP	-	Go into Standby mode	1	00 0000 0110 0011	$\overline{TO}$,$\overline{PD}$	
SUBLW	k	Subtract W from literal	1	11 110x kkkk kkkk	C,DC,Z	
XORLW	k	Exclusive OR literal with W	1	11 1010 kkkk kkkk	Z	

Note 1: When an I/O register is modified as a function of itself (e.g., `MOVF PORTA, 1`), the value used will be that value present on the pins themselves. For example, if the data latch is '1' for a pin configured as input and is driven low by an external device, the data will be written back with a '0'.

2: If this instruction is executed on the TMR0 register (and, where applicable, d = 1), the prescaler will be cleared if assigned to the Timer0 module.

3: If Program Counter (PC) is modified, or a conditional test is true, the instruction requires two cycles. The second cycle is executed as a `NOP`.

Note: Additional information on the mid-range instruction set is available in the PIC® Mid-Range MCU Family Reference Manual (DS33023).

11.2 MPLAB C Compilers for Various Device Families

The MPLAB C Compiler code development systems are complete ANSI C compilers for Microchip's PIC18, PIC24 and PIC32 families of microcontrollers and the dsPIC30 and dsPIC33 families of digital signal controllers. These compilers provide powerful integration capabilities, superior code optimization and ease of use.

For easy source level debugging, the compilers provide symbol information that is optimized to the MPLAB IDE debugger.

11.3 HI-TECH C for Various Device Families

The HI-TECH C Compiler code development systems are complete ANSI C compilers for Microchip's PIC family of microcontrollers and the dsPIC family of digital signal controllers. These compilers provide powerful integration capabilities, omniscient code generation and ease of use.

For easy source level debugging, the compilers provide symbol information that is optimized to the MPLAB IDE debugger.

The compilers include a macro assembler, linker, preprocessor, and one-step driver, and can run on multiple platforms.

11.4 MPASM Assembler

The MPASM Assembler is a full-featured, universal macro assembler for PIC10/12/16/18 MCUs.

The MPASM Assembler generates relocatable object files for the MPLINK Object Linker, Intel® standard HEX files, MAP files to detail memory usage and symbol reference, absolute LST files that contain source lines and generated machine code and COFF files for debugging.

The MPASM Assembler features include:

- Integration into MPLAB IDE projects
- User-defined macros to streamline assembly code
- Conditional assembly for multi-purpose source files
- Directives that allow complete control over the assembly process

11.5 MPLINK Object Linker/ MPLIB Object Librarian

The MPLINK Object Linker combines relocatable objects created by the MPASM Assembler and the MPLAB C18 C Compiler. It can link relocatable objects from precompiled libraries, using directives from a linker script.

The MPLIB Object Librarian manages the creation and modification of library files of precompiled code. When a routine from a library is called from a source file, only the modules that contain that routine will be linked in with the application. This allows large libraries to be used efficiently in many different applications.

The object linker/library features include:

- Efficient linking of single libraries instead of many smaller files
- Enhanced code maintainability by grouping related modules together
- Flexible creation of libraries with easy module listing, replacement, deletion and extraction

11.6 MPLAB Assembler, Linker and Librarian for Various Device Families

MPLAB Assembler produces relocatable machine code from symbolic assembly language for PIC24, PIC32 and dsPIC devices. MPLAB C Compiler uses the assembler to produce its object file. The assembler generates relocatable object files that can then be archived or linked with other relocatable object files and archives to create an executable file. Notable features of the assembler include:

- Support for the entire device instruction set
- Support for fixed-point and floating-point data
- Command line interface
- Rich directive set
- Flexible macro language
- MPLAB IDE compatibility

11.7 MPLAB SIM Software Simulator

The MPLAB SIM Software Simulator allows code development in a PC-hosted environment by simulating the PIC MCUs and dsPIC® DSCs on an instruction level. On any given instruction, the data areas can be examined or modified and stimuli can be applied from a comprehensive stimulus controller. Registers can be logged to files for further run-time analysis. The trace buffer and logic analyzer display extend the power of the simulator to record and track program execution, actions on I/O, most peripherals and internal registers.

The MPLAB SIM Software Simulator fully supports symbolic debugging using the MPLAB C Compilers, and the MPASM and MPLAB Assemblers. The software simulator offers the flexibility to develop and debug code outside of the hardware laboratory environment, making it an excellent, economical software development tool.

11.8 MPLAB REAL ICE In-Circuit Emulator System

MPLAB REAL ICE In-Circuit Emulator System is Microchip's next generation high-speed emulator for Microchip Flash DSC and MCU devices. It debugs and programs PIC® Flash MCUs and dsPIC® Flash DSCs with the easy-to-use, powerful graphical user interface of the MPLAB Integrated Development Environment (IDE), included with each kit.

The emulator is connected to the design engineer's PC using a high-speed USB 2.0 interface and is connected to the target with either a connector compatible with in-circuit debugger systems (RJ11) or with the new high-speed, noise tolerant, Low-Voltage Differential Signal (LVDS) interconnection (CAT5).

The emulator is field upgradable through future firmware downloads in MPLAB IDE. In upcoming releases of MPLAB IDE, new devices will be supported, and new features will be added. MPLAB REAL ICE offers significant advantages over competitive emulators including low-cost, full-speed emulation, run-time variable watches, trace analysis, complex breakpoints, a ruggedized probe interface and long (up to three meters) interconnection cables.

11.9 MPLAB ICD 3 In-Circuit Debugger System

MPLAB ICD 3 In-Circuit Debugger System is Microchip's most cost effective high-speed hardware debugger/programmer for Microchip Flash Digital Signal Controller (DSC) and microcontroller (MCU) devices. It debugs and programs PIC® Flash microcontrollers and dsPIC® DSCs with the powerful, yet easy-to-use graphical user interface of MPLAB Integrated Development Environment (IDE).

The MPLAB ICD 3 In-Circuit Debugger probe is connected to the design engineer's PC using a high-speed USB 2.0 interface and is connected to the target with a connector compatible with the MPLAB ICD 2 or MPLAB REAL ICE systems (RJ-11). MPLAB ICD 3 supports all MPLAB ICD 2 headers.

11.10 PICkit 3 In-Circuit Debugger/ Programmer and PICkit 3 Debug Express

The MPLAB PICkit 3 allows debugging and programming of PIC® and dsPIC® Flash microcontrollers at a most affordable price point using the powerful graphical user interface of the MPLAB Integrated Development Environment (IDE). The MPLAB PICkit 3 is connected to the design engineer's PC using a full speed USB interface and can be connected to the target via an Microchip debug (RJ-11) connector (compatible with MPLAB ICD 3 and MPLAB REAL ICE). The connector uses two device I/O pins and the reset line to implement in-circuit debugging and In-Circuit Serial Programming™.

The PICkit 3 Debug Express include the PICkit 3, demo board and microcontroller, hookup cables and CDROM with user's guide, lessons, tutorial, compiler and MPLAB IDE software.

12.1 DC Characteristics: PIC16F630/676-I (Industrial), PIC16F630/676-E (Extended)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended				
Param No.	**Sym**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
	VDD	**Supply Voltage**					FOSC < = 4 MHz:
D001			2.0	—	5.5	V	PIC16F630/676 with A/D off
D001A			2.2	—	5.5	V	PIC16F676 with A/D on, 0°C to +125°C
D001B			2.5	—	5.5	V	PIC16F676 with A/D on, -40°C to +125°C
D001C			3.0	—	5.5	V	4 MHz < FOSC < = 10 MHz
D001D			4.5	—	5.5	V	
D002	VDR	**RAM Data Retention Voltage(1)**	1.5*	—	—	V	Device in Sleep mode
D003	VPOR	**VDD Start Voltage** to ensure internal Power-on Reset signal	—	VSS	—	V	See section on Power-on Reset for details
D004	SVDD	**VDD Rise Rate** to ensure internal Power-on Reset signal	0.05*	—	—	V/ms	See section on Power-on Reset for details
D005	VBOD		—	2.1	—	V	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered in Sleep mode without losing RAM data.

TABLE 12-8: PIC16F676 A/D CONVERTER CHARACTERISTICS:

Param No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
A01	NR	Resolution	—	—	10 bits	bit	
A02	EABS	Total Absolute Error*	—	—	±1	LSb	VREF = 5.0V
A03	EIL	Integral Error	—	—	±1	LSb	VREF = 5.0V
A04	EDL	Differential Error	—	—	±1	LSb	No missing codes to 10 bits VREF = 5.0V
A05	EFS	Full Scale Range	2.2*	—	5.5*	V	
A06	EOFF	Offset Error	—	—	±1	LSb	VREF = 5.0V
A07	EGN	Gain Error	—	—	±1	LSb	VREF = 5.0V
A10	—	Monotonicity	—	guaranteed(3)	—	—	VSS ≤ VAIN ≤ VREF+
A20 A20A	VREF	Reference Voltage	2.0 2.5	—	— VDD + 0.3	V	 Absolute minimum to ensure 10-bit accuracy
A21	VREF	Reference V High (VDD or VREF)	VSS	—	VDD	V	
A25	VAIN	Analog Input Voltage	VSS	—	VREF	V	
A30	ZAIN	Recommended Impedance of Analog Voltage Source	—	—	10	kΩ	
A50	IREF	VREF Input Current(2)	10 —	— —	1000 10	μA μA	During VAIN acquisition. Based on differential of VHOLD to VAIN. During A/D conversion cycle.

* These parameters are characterized but not tested.

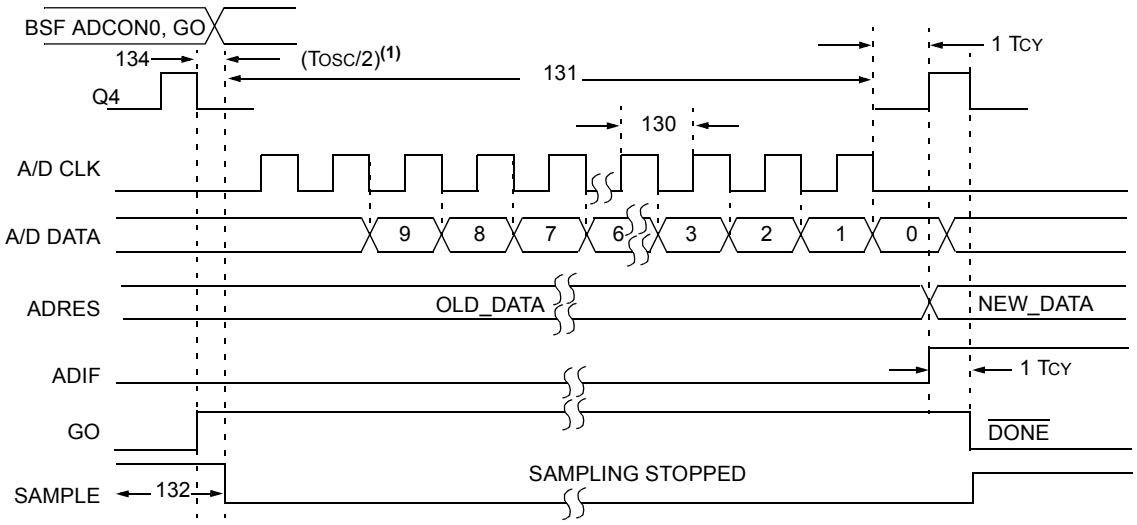
† Data in "Typ" column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: When A/D is off, it will not consume any current other than leakage current. The power-down current spec includes any such leakage from the A/D module.

2: VREF current is from External VREF or VDD pin, whichever is selected as reference input.

3: The A/D conversion result never decreases with an increase in the input voltage and has no missing codes.

FIGURE 12-10: PIC16F676 A/D CONVERSION TIMING (NORMAL MODE)



Note 1: If the A/D clock source is selected as RC, a time of TCY is added before the A/D clock starts. This allows the SLEEP instruction to be executed.

TABLE 12-9: PIC16F676 A/D CONVERSION REQUIREMENTS

Param No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
130	TAD	A/D Clock Period	1.6	—	—	µs	TOSC based, VREF ≥ 3.0V
			3.0*	—	—	µs	TOSC based, VREF full range
130	TAD	A/D Internal RC Oscillator Period					ADCS<1:0> = 11 (RC mode)
			3.0*	6.0	9.0*	µs	At VDD = 2.5V
			2.0*	4.0	6.0*	µs	At VDD = 5.0V
131	TCNV	Conversion Time (not including Acquisition Time)(1)	—	11	—	TAD	Set GO bit to new data in A/D result register
132	TACQ	Acquisition Time	**(Note 2)**	11.5	—	µs	
			5*	—	—	µs	The minimum time is the amplifier settling time. This may be used if the "new" input voltage has not changed by more than 1 LSb (i.e., 4.1 mV @ 4.096V) from the last sampled voltage (as stored on CHOLD).
134	TGO	Q4 to A/D Clock Start	—	TOSC/2	—	—	If the A/D clock source is selected as RC, a time of TCY is added before the A/D clock starts. This allows the SLEEP instruction to be executed.

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: ADRES register may be read on the following TCY cycle.

2: See Table 7-1 for minimum conditions.

FIGURE 13-9: TYPICAL IPD WITH A/D ENABLED vs. VDD OVER TEMP (-40°C TO +25°C)

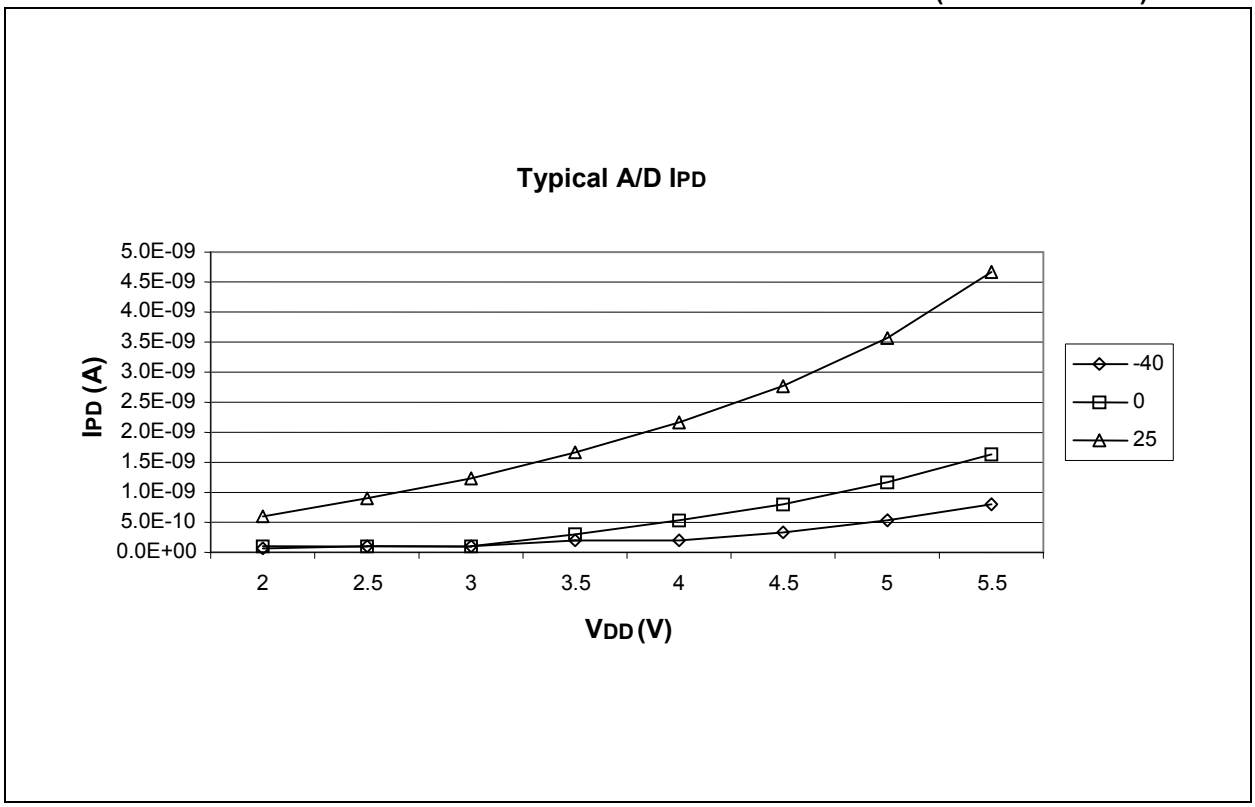
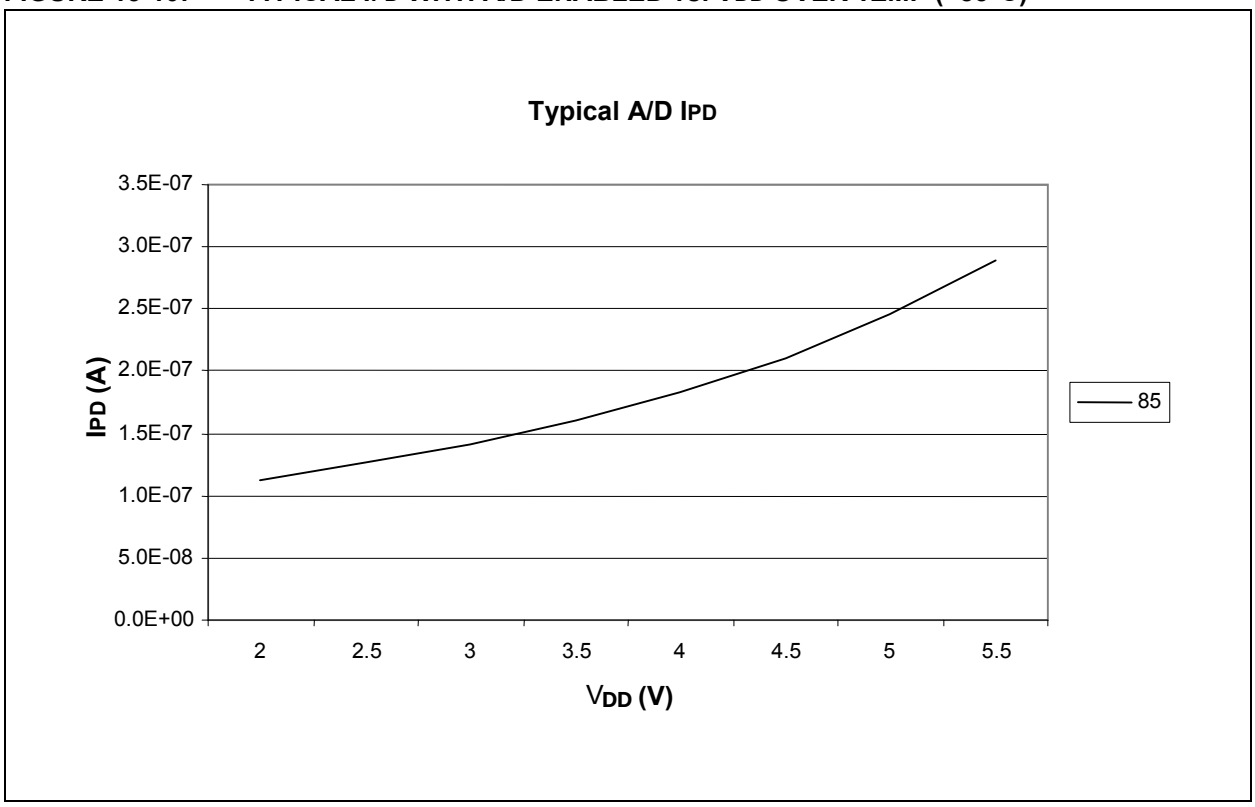
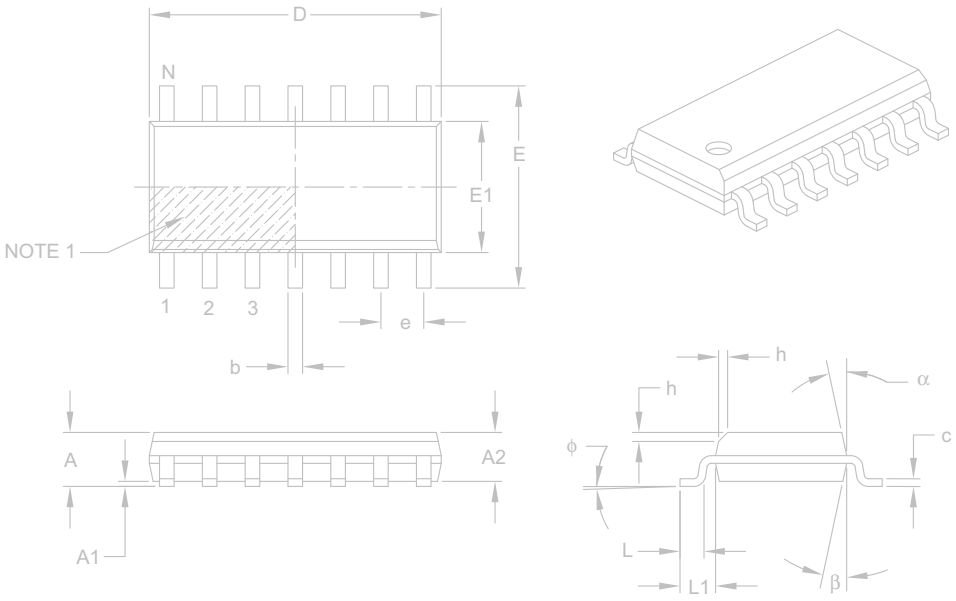


FIGURE 13-10: TYPICAL IPD WITH A/D ENABLED vs. VDD OVER TEMP (+85°C)



14-Lead Plastic Small Outline (SL) – Narrow, 3.90 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		14	
Pitch	e		1.27 BSC	
Overall Height	A	–	–	1.75
Molded Package Thickness	A2	1.25	–	–
Standoff §	A1	0.10	–	0.25
Overall Width	E		6.00 BSC	
Molded Package Width	E1		3.90 BSC	
Overall Length	D		8.65 BSC	
Chamfer (optional)	h	0.25	–	0.50
Foot Length	L	0.40	–	1.27
Footprint	L1		1.04 REF	
Foot Angle	ϕ	0°	–	8°
Lead Thickness	c	0.17	–	0.25
Lead Width	b	0.31	–	0.51
Mold Draft Angle Top	α	5°	–	15°
Mold Draft Angle Bottom	β	5°	–	15°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic.
3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.15 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-065B

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